Product Change Notification

Change Notification #: **117895 - 00**

Change Title: **Minor Change**
Select Tray and Boxed Intel® Xeon® Processor E5 Series and Intel® Xeon® Processor E7Series, PCN 117895-00, Product Material, Visual Appearance Change to Lidded Products

Date of Publication: **November 25, 2020**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	February 25, 2021

Description of Change to the Customer:

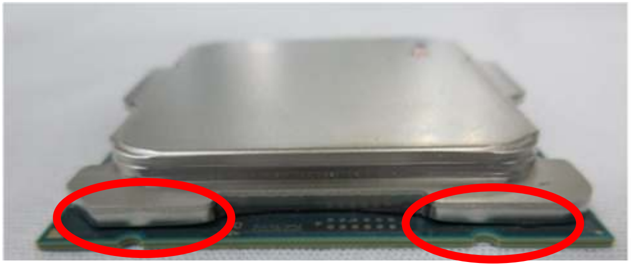
Due to tooling end-of-life constraints, discontinuing supplier support and process simplification, Intel will be changing their process for placing lids during the cure portion of the assembly process. This change will result in the following two visual changes to the package:

- There will be some additional sealant on the edge where the Lid meets the substrate.
- There will be a break in the sealant placed on the substrate just under the lid.

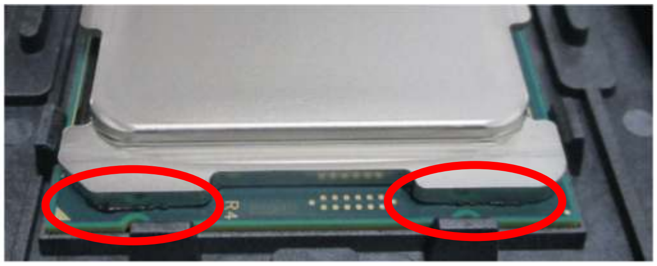
Note: The lid process referred to as "old placement process" in the pictures below uses an older technology placed by a specific tool that will end of life. The process referred to below as the "new placement process" although similar, is the next generation. Both the old placement process and the new placement process attach lids to units, accomplishing the same function. However, moving to the new placement process results in the two changes named within this notification.

1. **Additional Sealant noticeable on edge where substrate and lid meet, causing a squished-out appearance.**

Old Placement Process



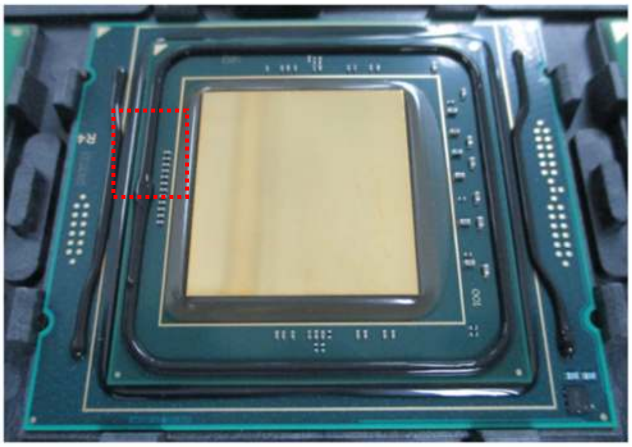
New Placement Process



(pictures are for reference only)

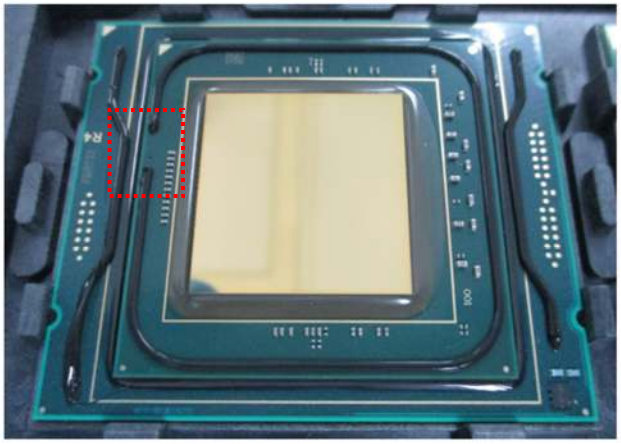
2. A break in the sealant opening on the substrate on the underside of the lid

Old Placement Process



☐ Sealant enclosed

New Placement Process



☐ Sealant Opening

(pictures for reference only)

These minor changes are visible to the customer upon inspection and will occur on the Select Tray and Boxed Intel® Xeon® Processor E5 Series and Intel® Xeon® Processor E7 Series listed in the Products Affected / Intel Ordering Codes table below.

Customer Impact of Change and Recommended Action:

This is a Minor change. There is no change to the Form, Fit or Function of the product as a result of this change. This is strictly a result of using different toolsets to accomplish the same task. Customers do not need to do anything as a result of this change.

Intel will not do a hard transition off of the old placement process to the new placement process. Therefore, customers should expect to see a limited mixture of finished goods until fully transitioned. The changes will start as early as February 25, 2021 as noted above.

Once Intel begins to transition, the older placement process will be discontinued and only the new process will be in place.

Please contact your Intel Representative with any questions or concerns regarding the change detailed in this notification.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	Stepping	S-Spec	MM#
Intel® Xeon® Processor E5-2695 v4	CM8066002023801	B0	S R2J1	945450
Intel® Xeon® Processor E5-2699 v4	CM8066002022506	B0	S R2JS	946675
Intel® Xeon® Processor E5-2683 v4	CM8066002023604	B0	S R2JT	946676
Intel® Xeon® Processor E5-2697 v4	CM8066002023907	B0	S R2JV	946678
Intel® Xeon® Processor E5-2698 v4	CM8066002024000	B0	S R2JW	946679
Intel® Xeon® Processor E5-2697A v4	CM8066002645900	B0	S R2K1	946684
Intel® Xeon® Processor E5-2690 v4	CM8066002030908	M0	S R2N2	947614
Intel® Xeon® Processor E5-2650 v4	CM8066002031103	M0	S R2N3	947616
Intel® Xeon® Processor E5-2660 v4	CM8066002031201	M0	S R2N4	947617
Intel® Xeon® Processor E5-2680 v4	CM8066002031501	M0	S R2N7	947620
Intel® Xeon® Processor E5-2650L v4	CM8066002033006	M0	S R2N8	947622
Intel® Xeon® Processor E5-2687W v4	CM8066002042802	M0	S R2NA	947624
Intel® Xeon® Processor E5-2658 v4	CM8066002044801	M0	S R2NB	947636
Intel® Xeon® Processor E5-2628L v4	CM8066002044903	M0	S R2NC	947637
Intel® Xeon® Processor E5-2648L v4	CM8066002189001	M0	S R2ND	947638

Marketing Name	Product Code	Stepping	S-Spec	MM#
Boxed Intel® Xeon® Processor E5-2690 v4	BX80660E52690V4	M0	S R2N2	948197
Boxed Intel® Xeon® Processor E5-2680 v4	BX80660E52680V4	M0	S R2N7	948200
Boxed Intel® Xeon® Processor E5-2687W v4	BX80660E52687V4	M0	S R2NA	948206
Intel® Xeon® Processor E7-8870 v4	CM8066902025802	B0	S R2S1	948733
Intel® Xeon® Processor E7-4850 v4	CM8066902026904	B0	S R2S2	948735
Intel® Xeon® Processor E7-4830 v4	CM8066902027102	B0	S R2S3	948737
Intel® Xeon® Processor E7-4820 v4	CM8066902027500	B0	S R2S4	948739
Intel® Xeon® Processor E7-4809 v4	CM8066902027604	B0	S R2S5	948741
Intel® Xeon® Processor E7-8867 v4	CM8066902028403	B0	S R2S6	948743
Intel® Xeon® Processor E7-8880 v4	CM8066902325500	B0	S R2S7	948745
Intel® Xeon® Processor E7-8860 v4	CM8066902325800	B0	S R2S8	948747
Intel® Xeon® Processor E7-8855 v4	CM8066902675600	B0	S R2S9	948749
Intel® Xeon® Processor E5-4650 v4	CM8066002028621	M0	S R2SA	948752
Intel® Xeon® Processor E5-4628L v4	CM8066002061000	M0	S R2SB	948754
Intel® Xeon® Processor E5-4660 v4	CM8066002062605	B0	S R2SD	948758
Intel® Xeon® Processor E5-4610 v4	CM8066002062800	M0	S R2SE	948762
Intel® Xeon® Processor E5-4667 v4	CM8066002064600	B0	S R2SF	948764
Intel® Xeon® Processor E5-4669 v4	CM8066002064800	B0	S R2SG	948767
Intel® Xeon® Processor E5-4620 v4	CM8066002883900	M0	S R2SJ	948771
Intel® Xeon® Processor E7-8891 v4	CM8066902027903	B0	S R2SQ	948869
Intel® Xeon® Processor E7-8893 v4	CM8066902065502	B0	S R2SR	948871
Intel® Xeon® Processor E7-8890 v4	CM8066902885200	B0	S R2SS	948873
Intel® Xeon® Processor E5-2689 v4	CM8066002648200	B0	S R2T7	949319
Intel® Xeon® Processor E5-2699A v4	CM8066003197800	B0	S R30Y	952190
Intel® Xeon® Processor E5-2699R v4	CM8066003216500	B0	S R31X	952514
Intel® Xeon® Processor E7-8894 v4	CM8066903251800	B0	S R32U	952962

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 25, 2020	00	Originally Published PCN

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